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LM341/LM78MXX Series 3-Terminal Positive Voltage Regulators

General Description

The LM341 and LM78MXX series of three-terminal positive voltage regulators employ built-in current limiting, thermal shutdown, and safe-operating area protection which makes them virtually immune to damage from output overloads.

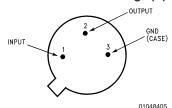
With adequate heatsinking, they can deliver in excess of 0.5A output current. Typical applications would include local (on-card) regulators which can eliminate the noise and degraded performance associated with single-point regulation.

Features

- Output current in excess of 0.5A
- No external components
- Internal thermal overload protection
- Internal short circuit current-limiting
- Output transistor safe-area compensation
- Available in TO-220, TO-39, and TO-252 D-PAK packages
- Output voltages of 5V, 12V, and 15V

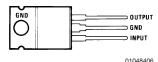
Connection Diagrams

TO-39 Metal Can Package (H)



Bottom View
Order Number LM78M05CH, LM78M12CH or LM78M15CH
See NS Package Number H03A

TO-220 Power Package (T)



Top View

Order Number LM341T-5.0, LM341T-12, LM341T-15, LM78M05CT, LM78M12CT or LM78M15CT See NS Package Number T03B



Top View Order Number LM78M05CDT See NS Package Number TD03B

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Lead Temperature (Soldering, 10 seconds)

TO-39 Package (H) 300°C TO-220 Package (T) 260°C Storage Temperature Range -65°C to +150°C **Operating Junction Temperature**

Range -40° C to $+125^{\circ}$ C Power Dissipation (Note 2) Internally Limited

Input Voltage

 $5V \le V_O \le 15V$ 35V ESD Susceptibility TBD

Electrical Characteristics

Limits in standard typeface are for $T_J = 25^{\circ}\text{C}$, and limits in **boldface type** apply over the -40°C to $+125^{\circ}\text{C}$ operating temperature range. Limits are guaranteed by production testing or correlation techniques using standard Statistical Quality Control (SQC) methods.

LM341-5.0, LM78M05C

Unless otherwise specified: V_{IN} = 10V, C_{IN} = 0.33 $\mu F,~C_O$ = 0.1 μF

Symbol	Parameter	Conditions		Min	Тур	Max	Units
V _O	Output Voltage	I _L = 500 mA		4.8	5.0	5.2	V
		5 mA ≤ I _L ≤ 500 mA		4.75	5.0	5.25	
		$P_D \le 7.5W, 7.5V \le V_{IN} \le$	$P_D \le 7.5W, 7.5V \le V_{IN} \le 20V$				
V _{R LINE}	Line Regulation	$7.2V \le V_{IN} \le 25V$	I _L = 100 mA			50	mV
			I _L = 500 mA			100	
V _{R LOAD}	Load Regulation	5 mA ≤ I _L ≤ 500 mA	5 mA ≤ I _L ≤ 500 mA			100	
I _Q	Quiescent Current	I _L = 500 mA	I _L = 500 mA		4	10.0	mA
ΔI_{Q}	Quiescent Current Change	5 mA ≤ I _L ≤ 500 mA				0.5	
		$7.5V \le V_{IN} \le 25V, I_{L} = 50$	00 mA			1.0	
V _n	Output Noise Voltage	f = 10 Hz to 100 kHz			40		μV
ΔV _{IN}	Ripple Rejection	f = 120 Hz, I _L = 500 mA					
$\frac{\Delta V_{O}}{\Delta V_{O}}$					78		dB
V _{IN}	Input Voltage Required	I _L = 500 mA		7.2			V
	to Maintain Line Regulation						
ΔV_{O}	Long Term Stability	I _L = 500 mA				20	mV/khrs

Electrical Characteristics

Limits in standard typeface are for $T_J = 25^{\circ}C$, and limits in **boldface type** apply over the $-40^{\circ}C$ to $+125^{\circ}C$ operating temperature range. Limits are guaranteed by production testing or correlation techniques using standard Statistical Quality Control (SQC) methods. (Continued)

LM341-12, LM78M12C

Unless otherwise specified: V_{IN} = 19V, C_{IN} = 0.33 $\mu F, \, C_O$ = 0.1 μF

Symbol	Parameter	Conditions		Min	Тур	Max	Units
V _O	Output Voltage	I _L = 500 mA		11.5	12	12.5	V
		5 mA ≤ I _L ≤ 500 mA		11.4	12	12.6	
		$P_D \le 7.5W, 14.8V \le V_{II}$	$P_D \le 7.5W, 14.8V \le V_{IN} \le 27V$				
V _{R LINE}	Line Regulation	$14.5 \text{V} \leq \text{V}_{\text{IN}} \leq 30 \text{V}$	I _L = 100 mA			120	mV
			I _L = 500 mA			240	
V _{R LOAD}	Load Regulation	5 mA ≤ I _L ≤ 500 mA	5 mA ≤ I _L ≤ 500 mA			240	
I _Q	Quiescent Current	I _L = 500 mA	I _L = 500 mA		4	10.0	mA
ΔI_{Q}	Quiescent Current Change	5 mA ≤ I _L ≤ 500 mA	5 mA ≤ I _L ≤ 500 mA			0.5	
		$14.8V \le V_{IN} \le 30V, I_{L} =$	500 mA			1.0	
V _n	Output Noise Voltage	f = 10 Hz to 100 kHz			75		μV
$\frac{\Delta V_{IN}}{\Delta V_{O}}$	Ripple Rejection	f = 120 Hz, I _L = 500 mA			71		dB
V _{IN}	Input Voltage Required	I _L = 500 mA		14.5			V
	to Maintain Line Regulation						
ΔV_{O}	Long Term Stability	I _L = 500 mA				48	mV/khrs

LM341-15, LM78M15C

Unless otherwise specified: V_{IN} = 23V, C_{IN} = 0.33 μF , C_{O} = 0.1 μF

Symbol	Parameter	Conditions		Min	Тур	Max	Units
Vo	Output Voltage	I _L = 500 mA		14.4	15	15.6	V
		5 mA ≤ I _L ≤ 500 mA		14.25	15	15.75	
		$P_D \le 7.5W, 18V \le V_{IN} \le 30V$					
V _{R LINE}	Line Regulation	$17.6V \le V_{IN} \le 30V$	I _L = 100 mA			150	mV
			I _L = 500 mA			300	
V _{R LOAD}	Load Regulation	5 mA ≤ I _L ≤ 500 mA				300	
IQ	Quiescent Current	I _L = 500 mA			4	10.0	mA
ΔI_Q	Quiescent Current Change	5 mA ≤ I _L ≤ 500 mA				0.5	
		$18V \le V_{IN} \le 30V, I_{L} = 50$	00 mA			1.0	
V _n	Output Noise Voltage	f = 10 Hz to 100 kHz			90		μV
$\frac{\Delta V_{IN}}{\Delta V_{O}}$	Ripple Rejection	f = 120 Hz, I _L = 500 mA			69		dB
V _{IN}	Input Voltage Required	I _L = 500 mA		17.6			V
	to Maintain Line Regulation						
ΔV_{O}	Long Term Stability	I _L = 500 mA				60	mV/khrs

Note 1: Absolute maximum ratings indicate limits beyond which damage to the component may occur. Electrical specifications do not apply when operating the device outside of its rated operating conditions.

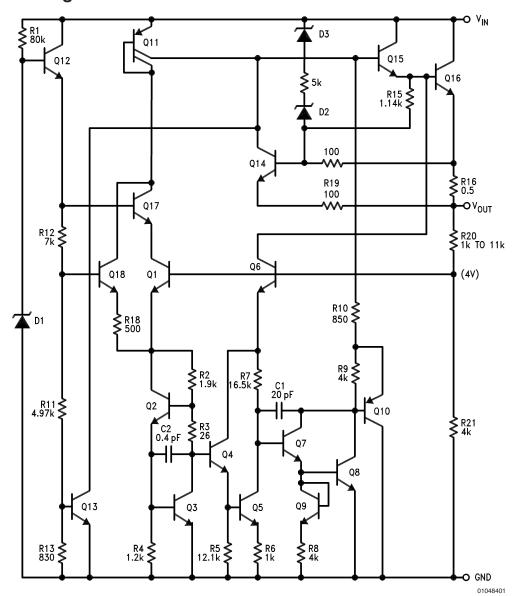
Note 2: The typical thermal resistance of the three package types is:

T (TO-220) package: $\theta_{(JA)}$ = 60 °C/W, $\theta_{(JC)}$ = 5 °C/W

H (TO-39) package: $\theta_{(JA)}$ = 120 °C/W, $\theta_{(JC)}$ = 18 °C/W

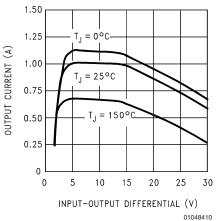
DT (TO-252) package: $\theta_{(JA)}$ = 92 °C/W, $\theta_{(JC)}$ = 10 °C/W

Schematic Diagram

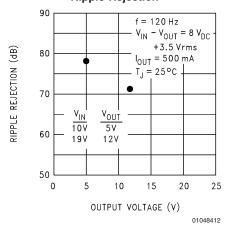


Typical Performance Characteristics

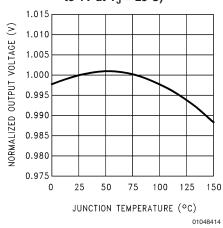




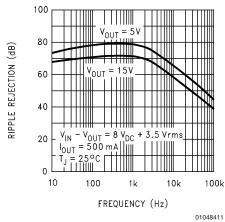




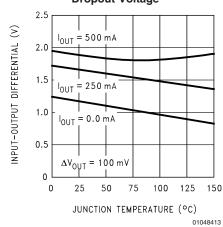
Output Voltage (Normalized to 1V at $T_J = 25^{\circ}C$)



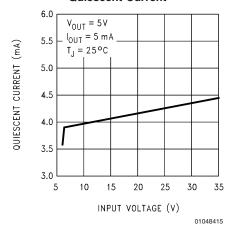
Ripple Rejection



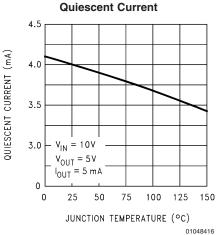
Dropout Voltage

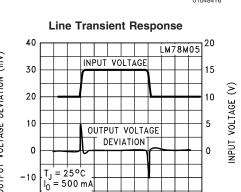


Quiescent Current



Typical Performance Characteristics (Continued)





OUTPUT VOLTAGE DEVIATION (mV) = 5.0 V2 6 10 12 TIME (μs) 01048407

Design Considerations

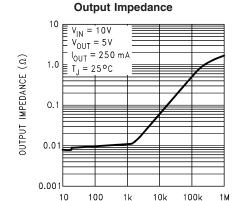
The LM78MXX/LM341XX fixed voltage regulator series has built-in thermal overload protection which prevents the device from being damaged due to excessive junction tem-

The regulators also contain internal short-circuit protection which limits the maximum output current, and safe-area protection for the pass transistor which reduces the shortcircuit current as the voltage across the pass transistor is increased.

Although the internal power dissipation is automatically limited, the maximum junction temperature of the device must be kept below +125°C in order to meet data sheet specifications. An adequate heatsink should be provided to assure this limit is not exceeded under worst-case operating conditions (maximum input voltage and load current) if reliable performance is to be obtained).

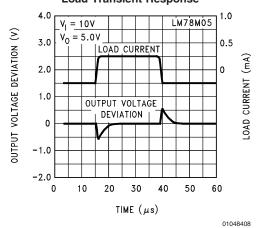
1.0 HEATSINK CONSIDERATIONS

When an integrated circuit operates with appreciable current, its junction temperature is elevated. It is important to quantify its thermal limits in order to achieve acceptable performance and reliability. This limit is determined by summing the individual parts consisting of a series of temperature rises from the semiconductor junction to the operating environment. A one-dimension steady-state model of con-



Load Transient Response

FREQUENCY (Hz)



01048417

duction heat transfer is demonstrated in The heat generated at the device junction flows through the die to the die attach pad, through the lead frame to the surrounding case material, to the printed circuit board, and eventually to the ambient environment. Below is a list of variables that may affect the thermal resistance and in turn the need for a heatsink.

R ^{θCA} (Application Variables)						
Mounting Pad Size, Material, & Location						
Placement of Mounting Pad						
PCB Size & Material						
Traces Length & Width						
Adjacent Heat Sources						
Volume of Air						
Air Flow						
Ambient Temperature						

Shape of Mounting Pad

Application Information

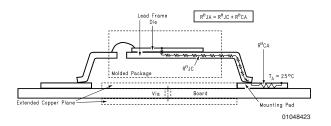


FIGURE 1. Cross-sectional view of Integrated Circuit
Mounted on a printed circuit board. Note that the case
temperature is measured at the point where the leads
contact with the mounting pad surface

The LM78MXX/LM341XX regulators have internal thermal shutdown to protect the device from over-heating. Under all possible operating conditions, the junction temperature of the LM78MXX/LM341XX must be within the range of 0°C to 125°C. A heatsink may be required depending on the maximum power dissipation and maximum ambient temperature of the application. To determine if a heatsink is needed, the power dissipated by the regulator, $P_{\rm D}$, must be calculated:

$$\begin{split} I_{IN} &= I_L + I_G \\ P_D &= (V_{IN} - V_{OUT}) \ I_L + V_{IN} I_G \end{split}$$

shows the voltages and currents which are present in the circuit.

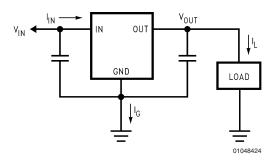


FIGURE 2. Power Dissipation Diagram

The next parameter which must be calculated is the maximum allowable temperature rise, $T_{\rm R}(\text{max})$:

$$\theta_{JA} = TR (max)/P_D$$

If the maximum allowable value for $\theta_{JA}{}^{\circ}C/w$ is found to be ${\geq}60{}^{\circ}C/W$ for TO-220 package or ${\geq}92{}^{\circ}C/W$ for TO-252 package, no heatsink is needed since the package alone will dissipate enough heat to satisfy these requirements. If the calculated value for θ_{JA} fall below these limits, a heatsink is required.

As a design aid, Table 1 shows the value of the θ_{JA} of TO-252 for different heatsink area. The copper patterns that

we used to measure these θ_{JA} are shown at the end of the Application Note Section. reflects the same test results as what are in the Table 1

shows the maximum allowable power dissipation vs. ambient temperature for the TO-252 device. shows the maximum allowable power dissipation vs. copper area (in²) for the TO-252 device. Please see AN1028 for power enhancement techniques to be used with TO-252 package.

Application Information (Continued)

TABLE 1. θ_{JA} Different Heatsink Area

Layout	Сорр	Thermal Resistance		
	Top Sice (in ²)*	Bottom Side (in ²)	(θ _{JA} , °C/W) TO-252	
1	0.0123	0	103	
2	0.066	0	87	
3	0.3	0	60	
4	0.53	0	54	
5	0.76	0	52	
6	1	0	47	
7	0	0.2	84	
8	0	0.4	70	
9	0	0.6	63	
10	0	0.8	57	
11	0	1	57	
12	0.066	0.066	89	
13	0.175	0.175	72	
14	0.284	0.284	61	
15	0.392	0.392	55	
16	0.5	0.5	53	

^{*}Tab of device attached to topside copper

Application Information (Continued)

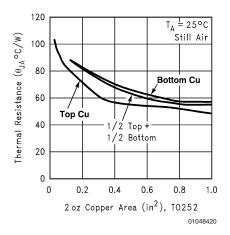


FIGURE 3. θ_{JA} vs. 2oz Copper Area for TO-252

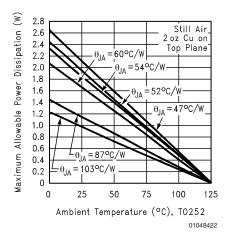


FIGURE 4. Maximum Allowable Power Dissipation vs.
Ambient Temperature for TO-252

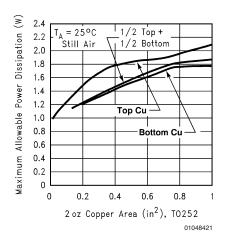
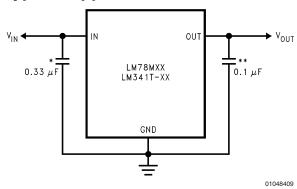


FIGURE 5. Maximum Allowable Power Dissipation vs. 2oz. Copper Area for TO-252

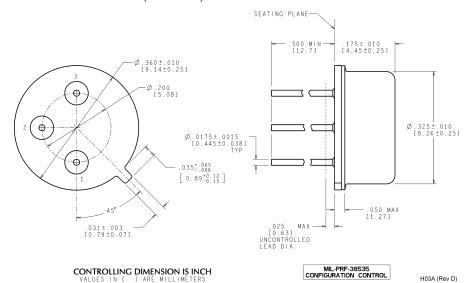
Typical Application



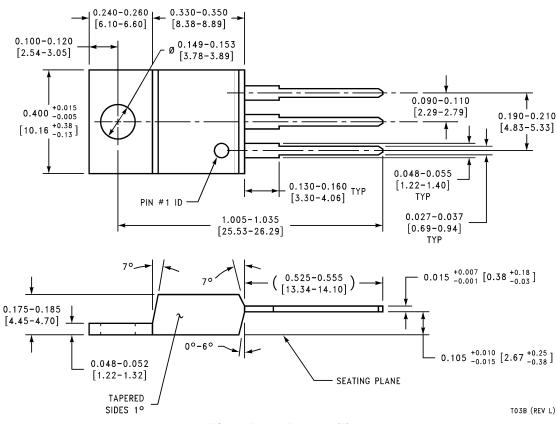
*Required if regulator input is more than 4 inches from input filter capacitor (or if no input filter capacitor is used).

^{**}Optional for improved transient response.

Physical Dimensions inches (millimeters) unless otherwise noted

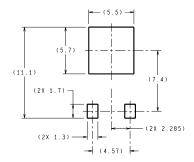


TO-39 Metal Can Package (H)
Order Number LM78M05CH, LM78M12CH or LM78M15CH
NS Package Number H03A



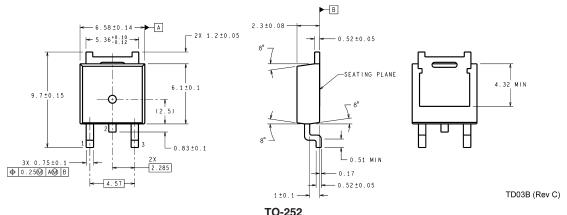
TO-220 Power Package (T)
Order Number LM341T-5.0, LM341T-12, LM341T-15, LM78M05CT, LM78M12CT or LM78M15CT
NS Package Number T03B

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



DIMENSIONS ARE IN MILLIMETERS

LAND PATTERN RECOMMENDATION



Order Number LM78M05CDT NS Package Number TD03B

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